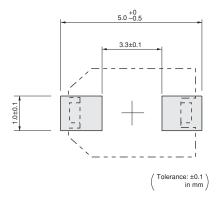
Mounting

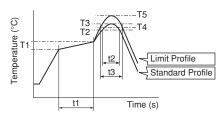
■ Land Pattern



■ Soldering Profile

■ Reflow Soldering Profile

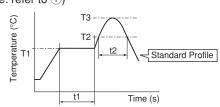
①Soldering profile for Lead-free solder (96.5Sn/3Ag/0.5Cu)



Standard Profile						
Pre-h	eating	Heating		Peak Temperature	Cycle	
Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	(T3)	of Reflow	
150 to 180°C	60 to 120sec.	220°C	30 to 60sec.	245±3°C	2 times	

Limit Profile						
Pre-h	eating	Heating		Peak	Cycle	
Temp. (T1)	Time (t1)	Temp. (T4)	Time (t3)	Temperature (T5)	of Reflow	
150 to 180°C	60 to 120sec.	230°C	30 to 50sec.	260 +5/-0°C	2 times	

②Soldering profile for Eutectic solder (63Sn/37Pb) (Limit profile: refer to 1)



Standard Profile						
Pre-h	eating	Heating		Peak	Cycle	
Temp. (T1)	Time (t1)	Temp. (T2)	Time (t2)	Temperature (T3)	of Reflow	
150°C	60 to 120sec.	183°C	30sec.	230 +5/-0°C	1 time	

Soldering Iron

Standard Profile				
Temperature of Soldering Iron Tip	Soldering Time	Soldering Iron Power Output	Cycle of Soldering Iron	
350±10°C	3sec. max.	30W max.	1 time	